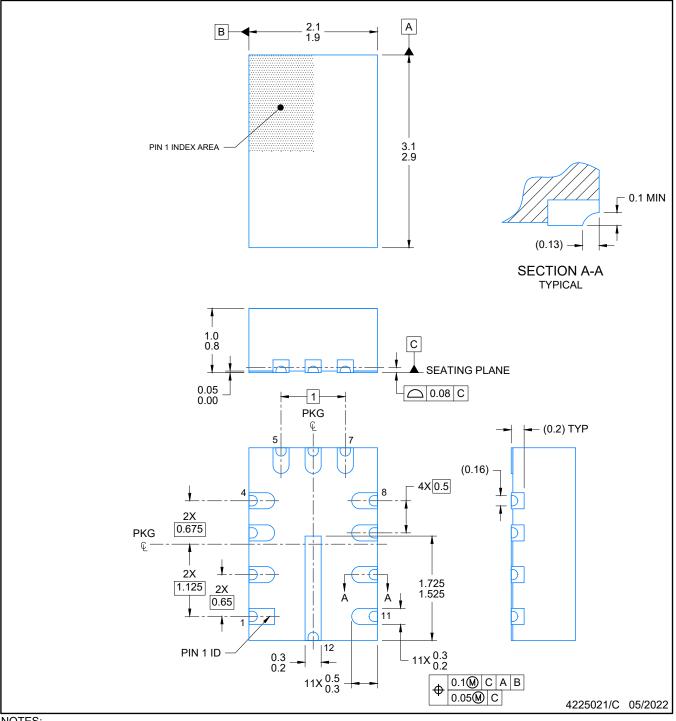
RNX0012C

PACKAGE OUTLINE VQFN-HR - 1 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD



NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing 1. per ASME Y14.5M.
- 2. This drawing is subject to change without notice.

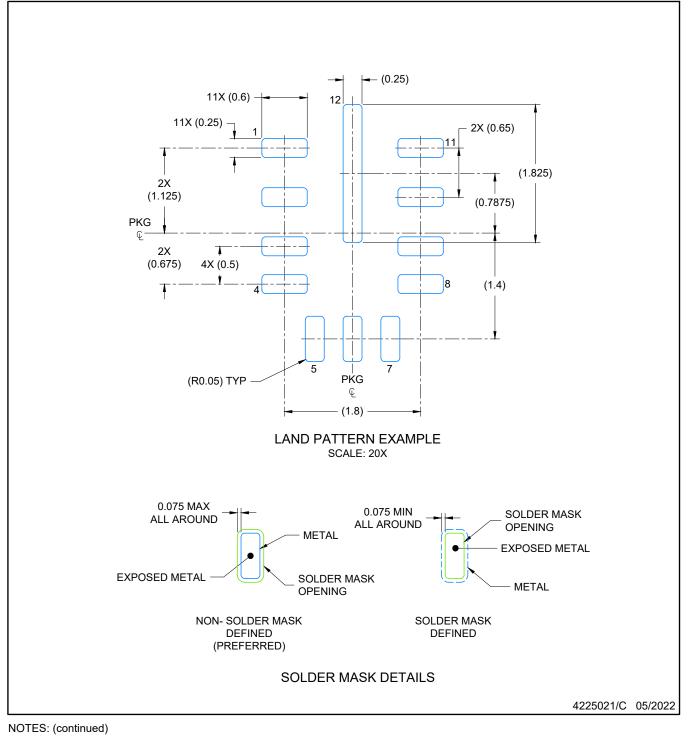


RNX0012C

EXAMPLE BOARD LAYOUT

VQFN-HR - 1 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD



- 3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- 4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

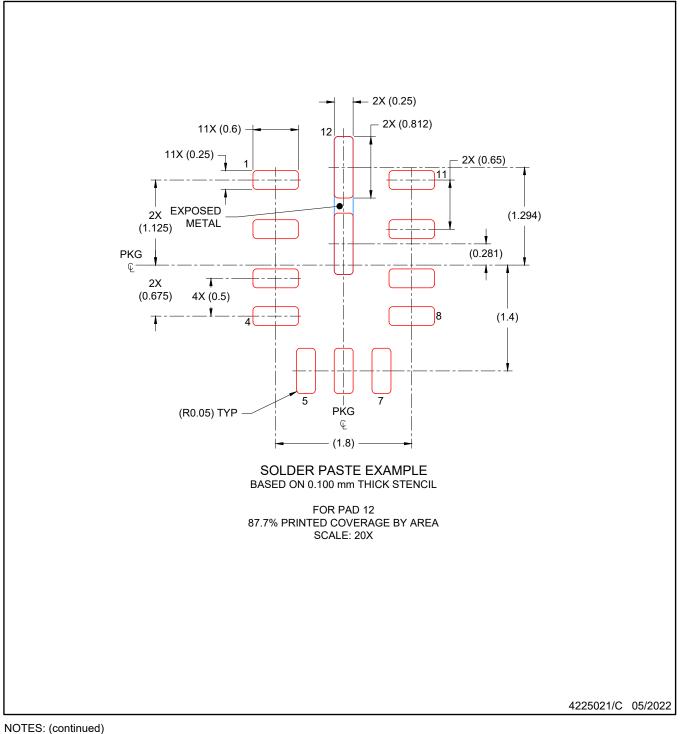


RNX0012C

EXAMPLE STENCIL DESIGN

VQFN-HR - 1 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD



5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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